

|                     |       |
|---------------------|-------|
| $V_{DSS}$           | 650V  |
| $R_{DS(on)}$ (Typ.) | 120mΩ |
| $I_D^{*1}$          | 21A   |
| $P_D$               | 103W  |

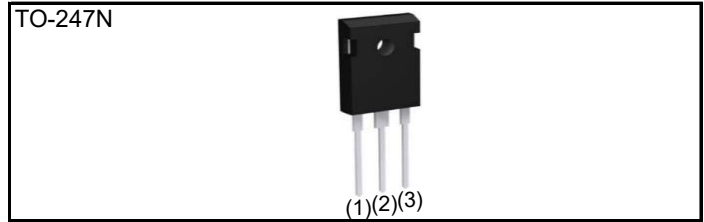
### ●Features

- 1) Qualified to AEC-Q101
- 2) Low on-resistance
- 3) Fast switching speed
- 4) Fast reverse recovery
- 5) Easy to parallel
- 6) Simple to drive
- 7) Pb-free lead plating ; RoHS compliant

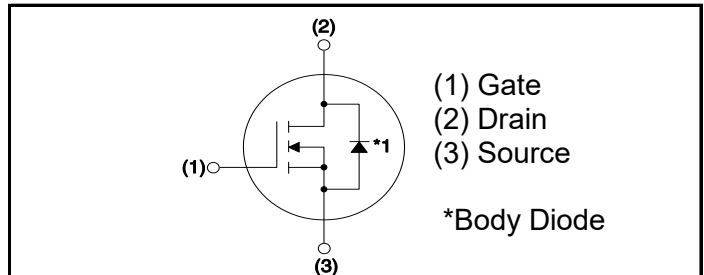
### ●Application

- Automobile
- Switch mode power supplies

### ●Outline



### ●Inner circuit



### ●Packaging specifications

| Type | Packing                   | Tube      |
|------|---------------------------|-----------|
|      | Reel size (mm)            | -         |
|      | Tape width (mm)           | -         |
|      | Basic ordering unit (pcs) | 30        |
|      | Taping code               | C11       |
|      | Marking                   | SCT3120AL |

### ●Absolute maximum ratings ( $T_a = 25^\circ\text{C}$ )

| Parameter                                                    | Symbol                    | Value       | Unit             |
|--------------------------------------------------------------|---------------------------|-------------|------------------|
| Drain - Source Voltage                                       | $V_{DSS}$                 | 650         | V                |
| Continuous Drain current                                     | $T_c = 25^\circ\text{C}$  | $I_D^{*1}$  | 21<br>A          |
|                                                              | $T_c = 100^\circ\text{C}$ | $I_D^{*1}$  | 15<br>A          |
| Pulsed Drain current                                         | $I_{D,pulse}^{*2}$        | 52          | A                |
| Gate - Source voltage (DC)                                   | $V_{GSS}$                 | -4 to +22   | V                |
| Gate - Source surge voltage ( $t_{surge} < 300\text{nsec}$ ) | $V_{GSS,surge}^{*3}$      | -4 to +26   | V                |
| Recommended drive voltage                                    | $V_{GS,op}^{*4}$          | 0 / +18     | V                |
| Junction temperature                                         | $T_j$                     | 175         | $^\circ\text{C}$ |
| Range of storage temperature                                 | $T_{stg}$                 | -55 to +175 | $^\circ\text{C}$ |

**●Electrical characteristics** ( $T_a = 25^\circ\text{C}$ )

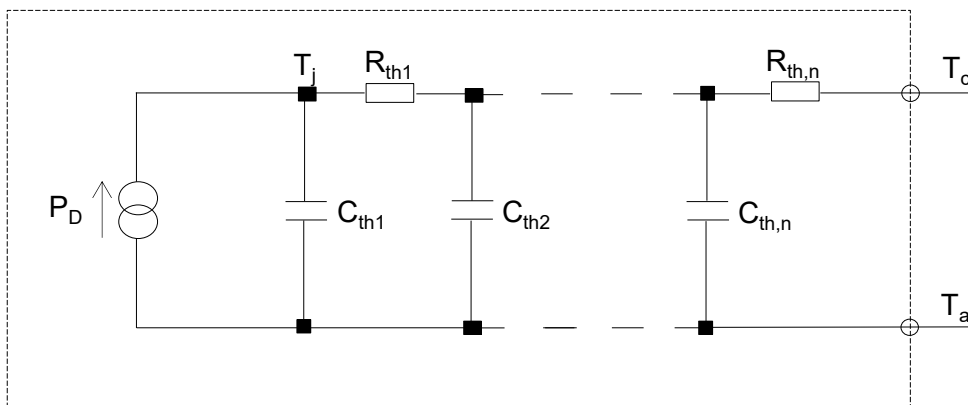
| Parameter                                   | Symbol            | Conditions                                                                                          | Values     |            |          | Unit          |
|---------------------------------------------|-------------------|-----------------------------------------------------------------------------------------------------|------------|------------|----------|---------------|
|                                             |                   |                                                                                                     | Min.       | Typ.       | Max.     |               |
| Drain - Source breakdown voltage            | $V_{(BR)DSS}$     | $V_{GS} = 0\text{V}, I_D = 1\text{mA}$<br>$T_j = 25^\circ\text{C}$<br>$T_j = -55^\circ\text{C}$     | 650<br>650 | -<br>-     | -<br>-   | V             |
| Zero Gate voltage Drain current             | $I_{DSS}$         | $V_{GS} = 0\text{V}, V_{DS} = 650\text{V}$<br>$T_j = 25^\circ\text{C}$<br>$T_j = 150^\circ\text{C}$ | -<br>-     | 1<br>2     | 10<br>-  | $\mu\text{A}$ |
| Gate - Source leakage current               | $I_{GSS+}$        | $V_{GS} = +22\text{V}, V_{DS} = 0\text{V}$                                                          | -          | -          | 100      | nA            |
| Gate - Source leakage current               | $I_{GSS-}$        | $V_{GS} = -4\text{V}, V_{DS} = 0\text{V}$                                                           | -          | -          | -100     | nA            |
| Gate threshold voltage                      | $V_{GS(th)}$      | $V_{DS} = 10\text{V}, I_D = 3.33\text{mA}$                                                          | 2.7        | -          | 5.6      | V             |
| Static Drain - Source on - state resistance | $R_{DS(on)}^{*5}$ | $V_{GS} = 18\text{V}, I_D = 6.7\text{A}$<br>$T_j = 25^\circ\text{C}$<br>$T_j = 150^\circ\text{C}$   | -<br>-     | 120<br>172 | 156<br>- | m $\Omega$    |
| Gate input resistance                       | $R_G$             | $f = 1\text{MHz}, \text{open drain}$                                                                | -          | 18         | -        | $\Omega$      |

**●Thermal resistance**

| Parameter                           | Symbol     | Values |      |      | Unit               |
|-------------------------------------|------------|--------|------|------|--------------------|
|                                     |            | Min.   | Typ. | Max. |                    |
| Thermal resistance, junction - case | $R_{thJC}$ | -      | 1.12 | 1.46 | $^\circ\text{C/W}$ |

**●Typical Transient Thermal Characteristics**

| Symbol    | Value    | Unit | Symbol    | Value    | Unit |
|-----------|----------|------|-----------|----------|------|
| $R_{th1}$ | 1.11E-01 | K/W  | $C_{th1}$ | 8.73E-04 | Ws/K |
| $R_{th2}$ | 7.09E-01 |      | $C_{th2}$ | 5.10E-03 |      |
| $R_{th3}$ | 3.01E-01 |      | $C_{th3}$ | 2.94E-02 |      |



●Electrical characteristics (T<sub>a</sub> = 25°C)

| Parameter                                    | Symbol            | Conditions                                                                                            | Values |      |      | Unit    |
|----------------------------------------------|-------------------|-------------------------------------------------------------------------------------------------------|--------|------|------|---------|
|                                              |                   |                                                                                                       | Min.   | Typ. | Max. |         |
| Transconductance                             | $g_{fs}^{*5}$     | $V_{DS} = 10V, I_D = 6.7A$                                                                            | -      | 2.7  | -    | S       |
| Input capacitance                            | $C_{iss}$         | $V_{GS} = 0V$                                                                                         | -      | 460  | -    | pF      |
| Output capacitance                           | $C_{oss}$         | $V_{DS} = 500V$                                                                                       | -      | 35   | -    |         |
| Reverse transfer capacitance                 | $C_{rss}$         | $f = 1MHz$                                                                                            | -      | 16   | -    |         |
| Effective output capacitance, energy related | $C_{o(er)}$       | $V_{GS} = 0V$<br>$V_{DS} = 0V \text{ to } 300V$                                                       | -      | 70   | -    | pF      |
| Total Gate charge                            | $Q_g^{*5}$        | $V_{DS} = 300V$<br>$I_D = 6.7A$                                                                       | -      | 38   | -    | nC      |
| Gate - Source charge                         | $Q_{gs}^{*5}$     | $V_{GS} = 18V$                                                                                        | -      | 10   | -    |         |
| Gate - Drain charge                          | $Q_{gd}^{*5}$     | See Fig. 1-1.                                                                                         | -      | 18   | -    |         |
| Turn - on delay time                         | $t_{d(on)}^{*5}$  | $V_{DS} = 300V$<br>$I_D = 6.7A$                                                                       | -      | 14   | -    | ns      |
| Rise time                                    | $t_r^{*5}$        | $V_{GS} = 0V/+18V$                                                                                    | -      | 21   | -    |         |
| Turn - off delay time                        | $t_{d(off)}^{*5}$ | $R_G = 0\Omega$<br>$R_L = 45\Omega$                                                                   | -      | 23   | -    |         |
| Fall time                                    | $t_f^{*5}$        | See Fig. 1-1, 1-2.                                                                                    | -      | 14   | -    |         |
| Turn - on switching loss                     | $E_{on}^{*5}$     | $V_{DS} = 300V$<br>$V_{GS}=0V/18V, I_D = 6.7A$<br>$R_G = 0\Omega, L = 500\mu H$                       | -      | 29   | -    | $\mu J$ |
| Turn - off switching loss                    | $E_{off}^{*5}$    | $E_{on}$ includes diode reverse recovery<br>$L_\sigma = 50nH, C_\sigma = 200pF$<br>See Fig. 2-1, 2-2. | -      | 3    | -    |         |

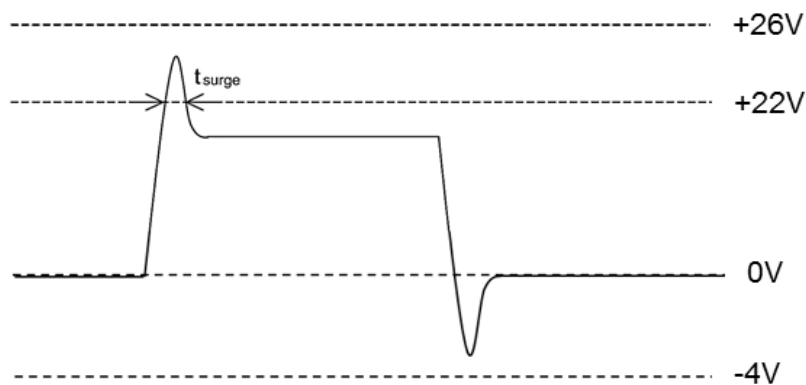
**●Body diode electrical characteristics (Source-Drain) ( $T_a = 25^\circ\text{C}$ )**

| Parameter                              | Symbol       | Conditions                                                                       | Values                                                                  |      |      | Unit |
|----------------------------------------|--------------|----------------------------------------------------------------------------------|-------------------------------------------------------------------------|------|------|------|
|                                        |              |                                                                                  | Min.                                                                    | Typ. | Max. |      |
| Body diode continuous, forward current | $I_S$ *1     | $T_c = 25^\circ\text{C}$                                                         | -                                                                       | -    | 21   | A    |
| Body diode direct current, pulsed      | $I_{SM}$ *2  |                                                                                  | -                                                                       | -    | 52   | A    |
| Forward voltage                        | $V_{SD}$ *5  | $V_{GS} = 0\text{V}, I_D = 6.7\text{A}$                                          | -                                                                       | 3.2  | -    | V    |
| Reverse recovery time                  | $t_{rr}$ *5  | $I_F = 6.7\text{A}$<br>$V_R = 300\text{V}$<br>$di/dt = 1100\text{A}/\mu\text{s}$ | -                                                                       | 13   | -    | ns   |
| Reverse recovery charge                | $Q_{rr}$ *5  |                                                                                  | -                                                                       | 35   | -    | nC   |
| Peak reverse recovery current          | $I_{rrm}$ *5 |                                                                                  | $L_\sigma = 50\text{nH}, C_\sigma = 200\text{pF}$<br>See Fig. 3-1, 3-2. | -    | 6    | -    |

\*1 Limited by maximum temperature allowed.

\*2  $P_W \leq 10\mu\text{s}$ , Duty cycle  $\leq 1\%$

\*3 Example of acceptable  $V_{GS}$  waveform



\*4 Please be advised not to use SiC-MOSFETs with  $V_{GS}$  below 13V as doing so may cause thermal runaway.

\*5 Pulsed

●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

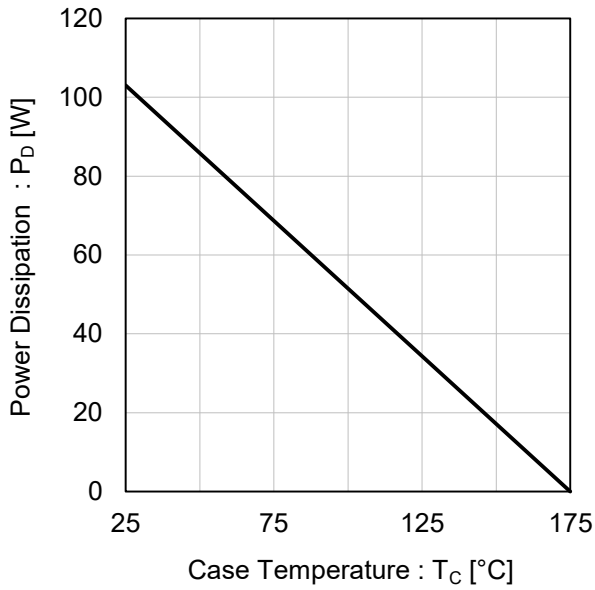


Fig.2 Maximum Safe Operating Area

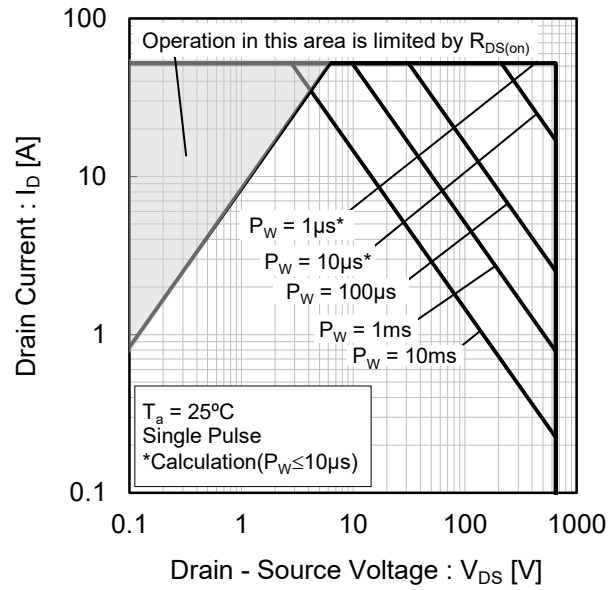
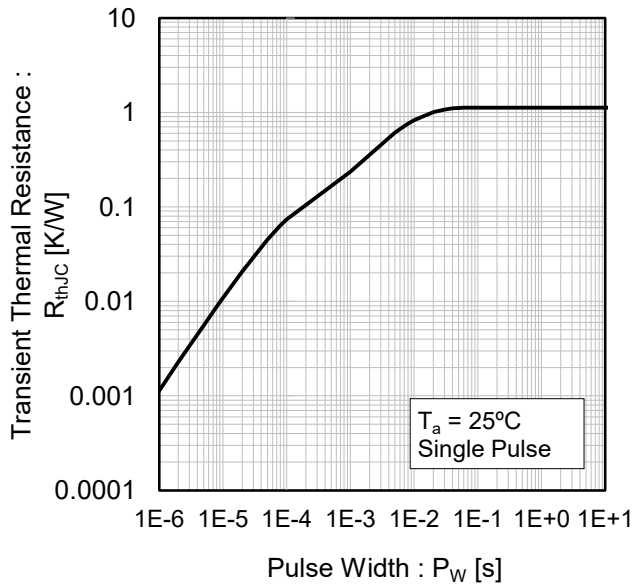


Fig.3 Typical Transient Thermal Resistance vs. Pulse Width



●Electrical characteristic curves

Fig.4 Typical Output Characteristics(I)

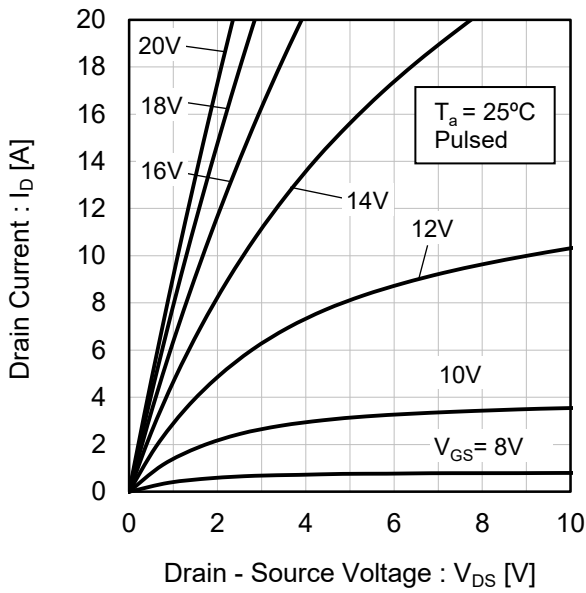


Fig.5 Typical Output Characteristics(II)

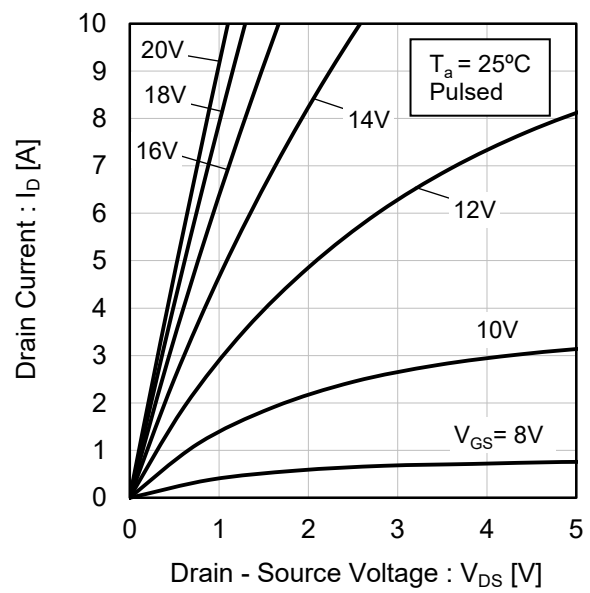
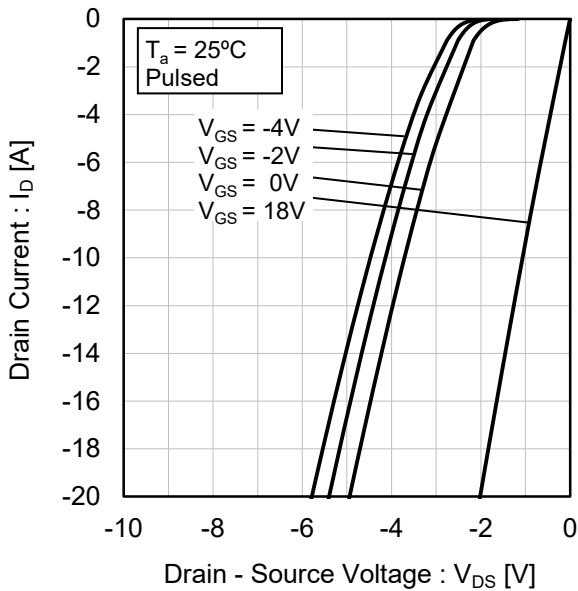


Fig.6  $T_j = 25^\circ\text{C}$  3rd Quadrant Characteristics



●Electrical characteristic curves

Fig.7  $T_j = 150^\circ\text{C}$  Typical Output Characteristics(I)

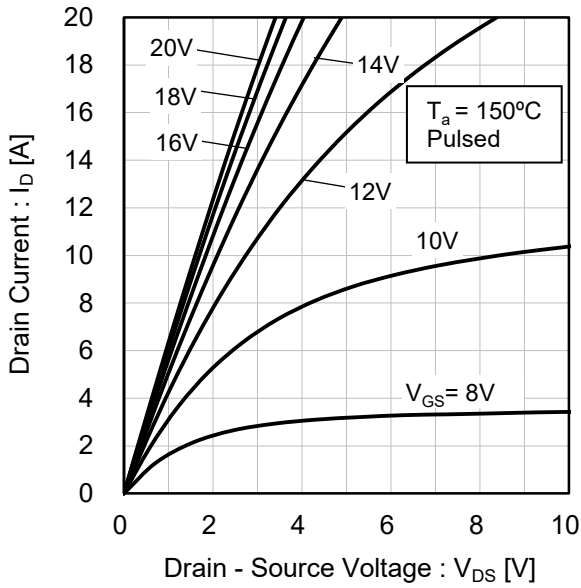


Fig.8  $T_j = 150^\circ\text{C}$  Typical Output Characteristics(II)

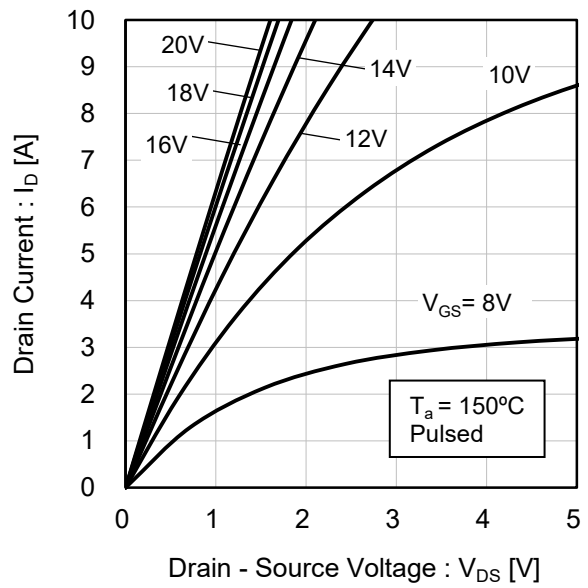


Fig.9  $T_j = 150^\circ\text{C}$  3rd Quadrant Characteristics

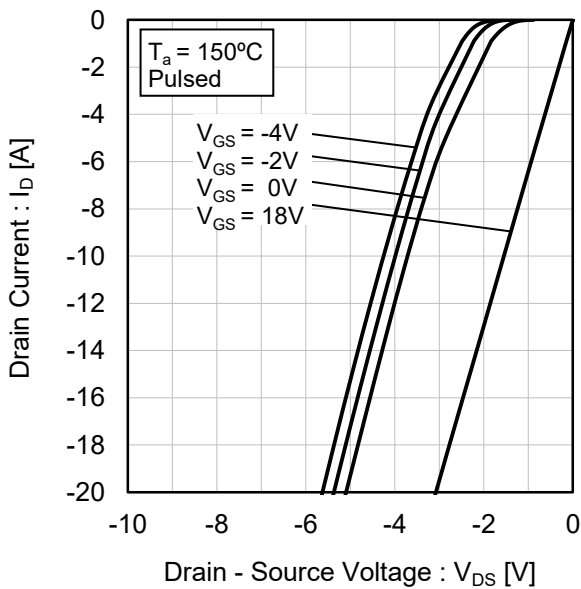
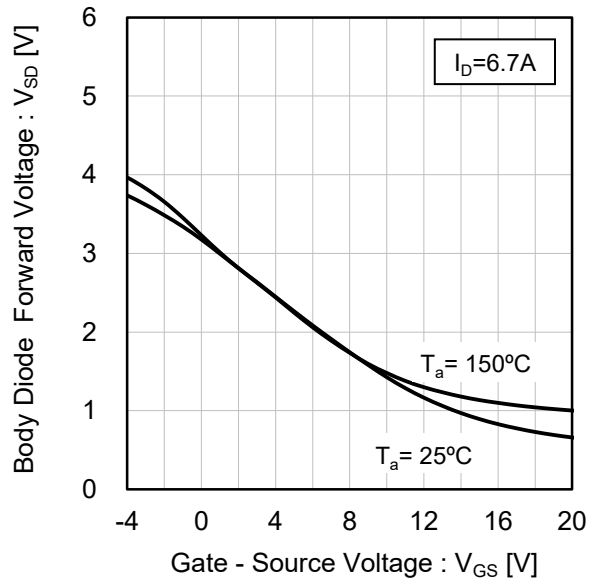


Fig.10 Body Diode Forward Voltage vs. Gate - Source Voltage



●Electrical characteristic curves

Fig.11 Typical Transfer Characteristics (I)

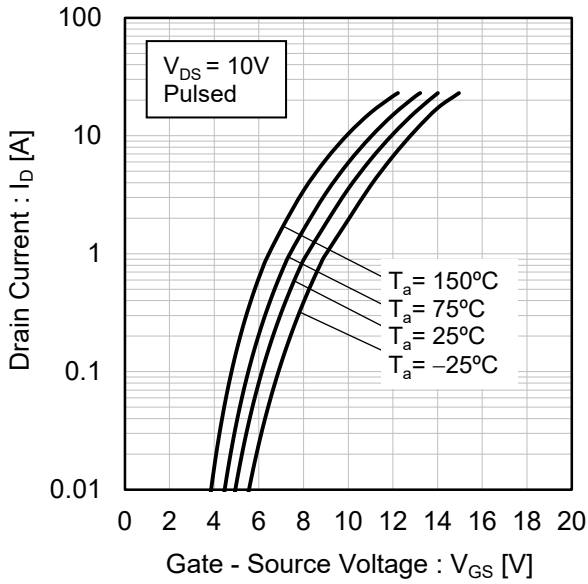


Fig.12 Typical Transfer Characteristics (II)

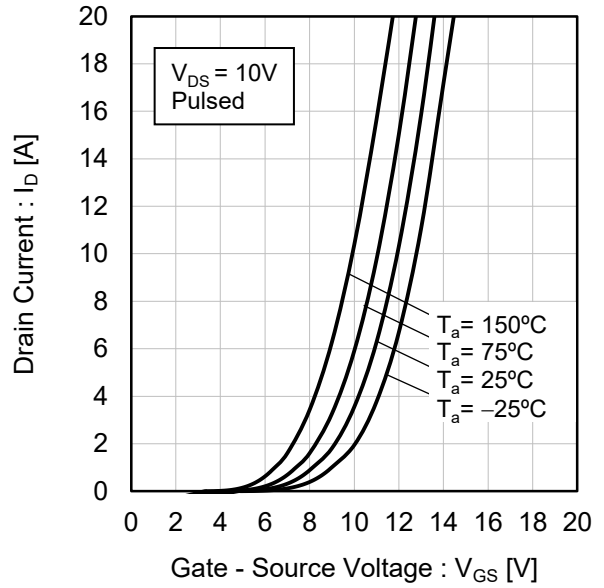


Fig.13 Gate Threshold Voltage vs. Junction Temperature

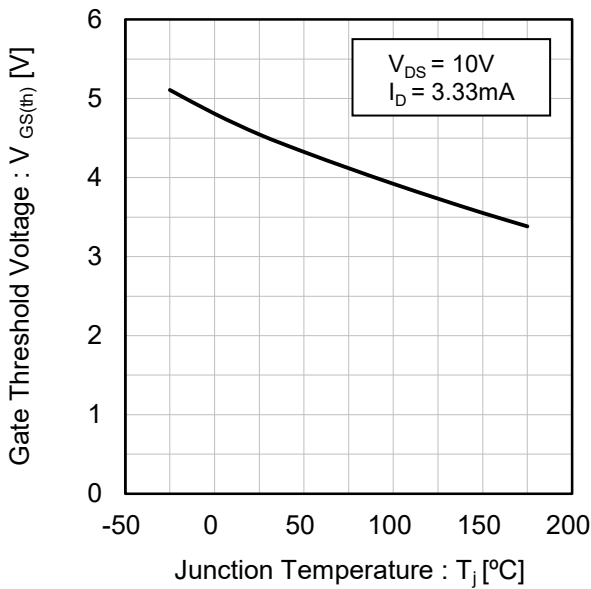
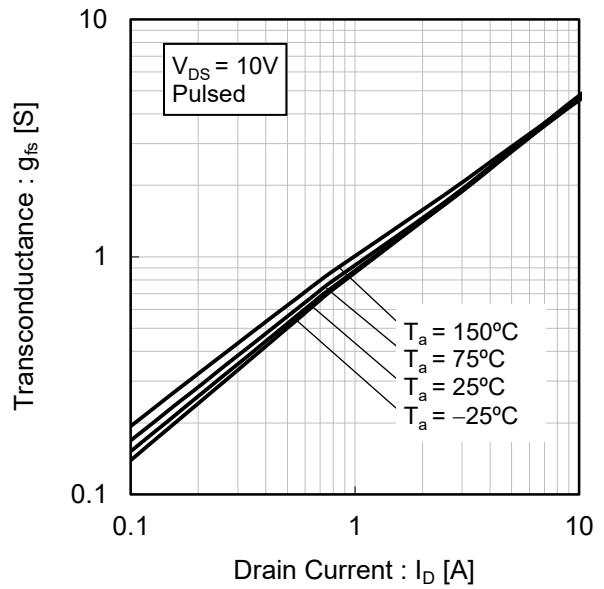


Fig.14 Transconductance vs. Drain Current



●Electrical characteristic curves

Fig.15 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

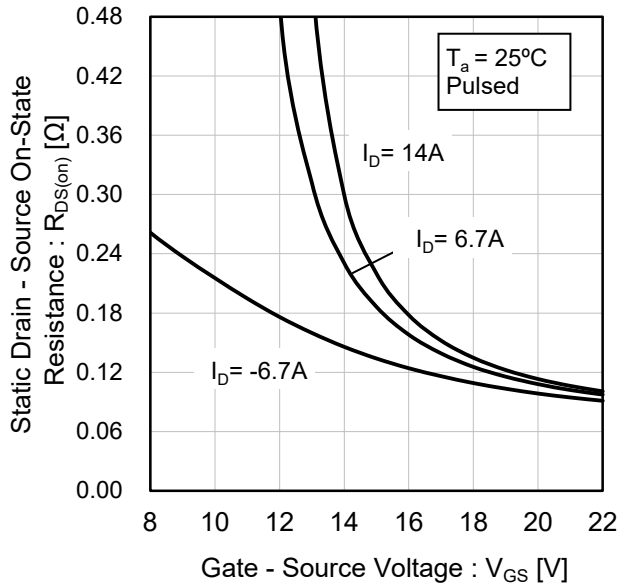


Fig.16 Static Drain - Source On - State Resistance vs. Junction Temperature

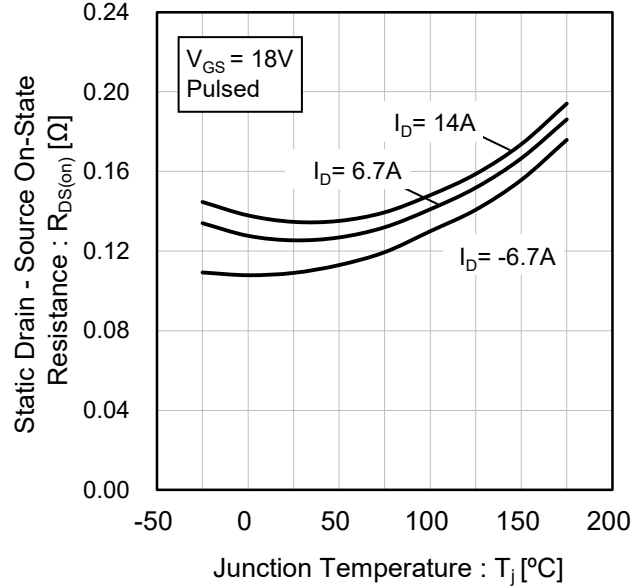


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current

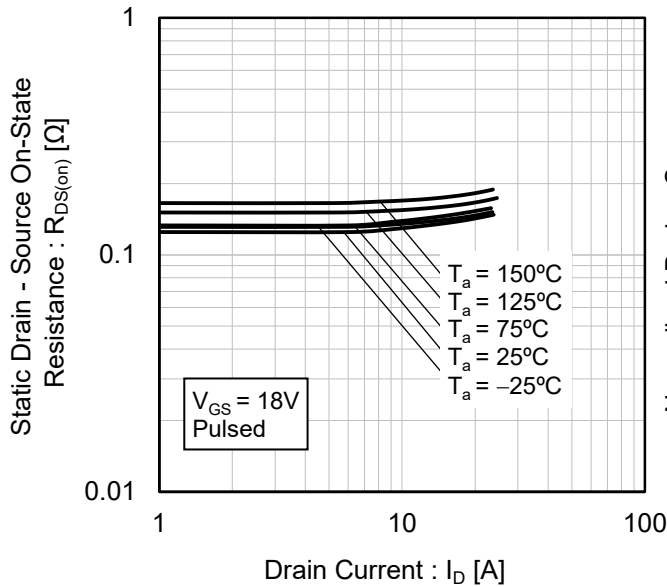
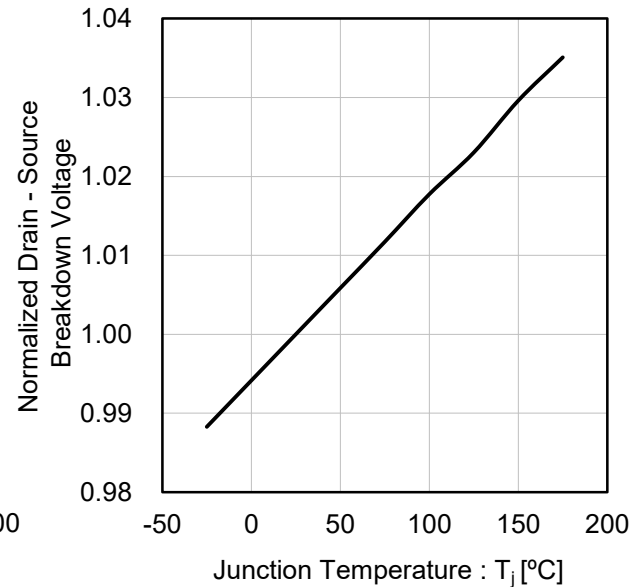


Fig.18 Normalized Drain - Source Breakdown Voltage vs. Junction Temperature



●Electrical characteristic curves

Fig.19 Typical Capacitance vs. Drain - Source Voltage

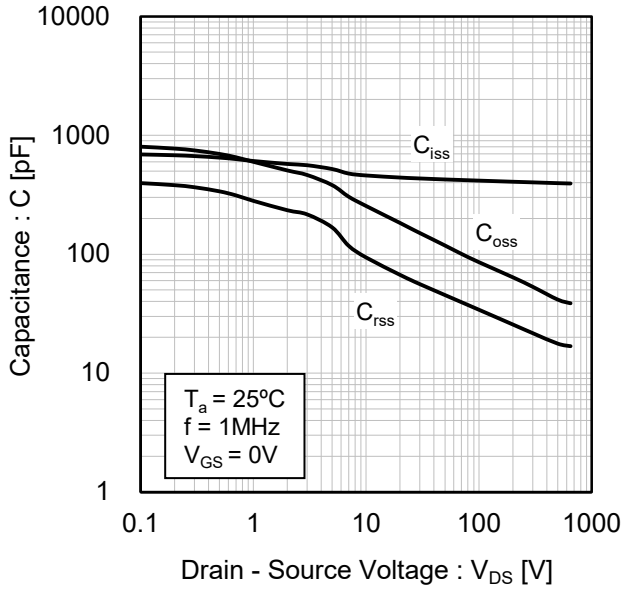


Fig.20  $C_{oss}$  Stored Energy

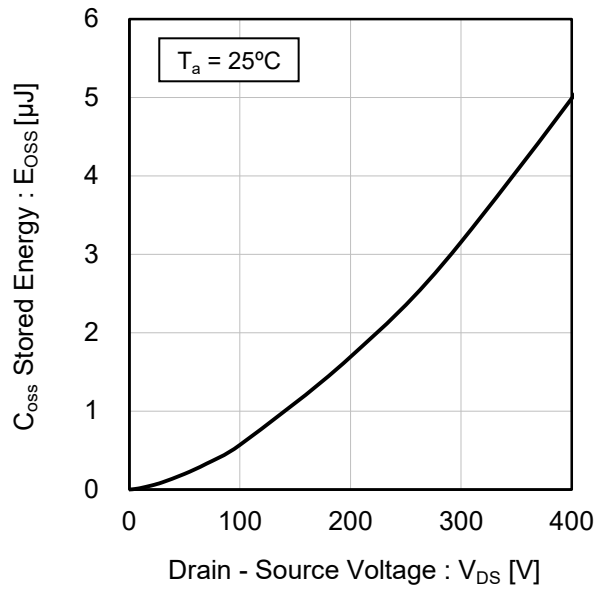
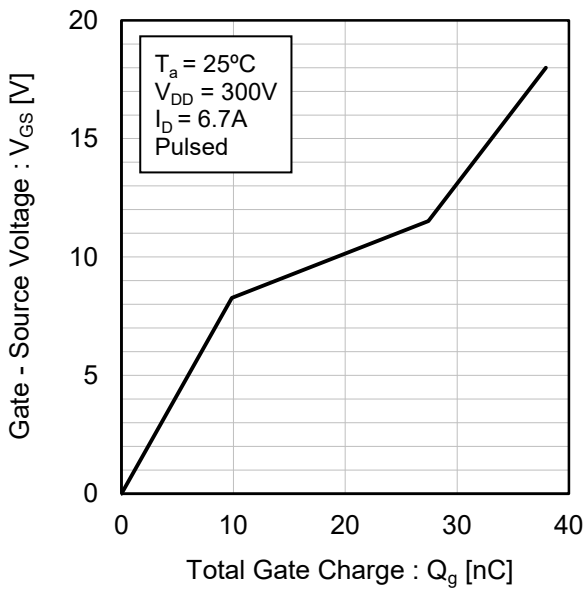
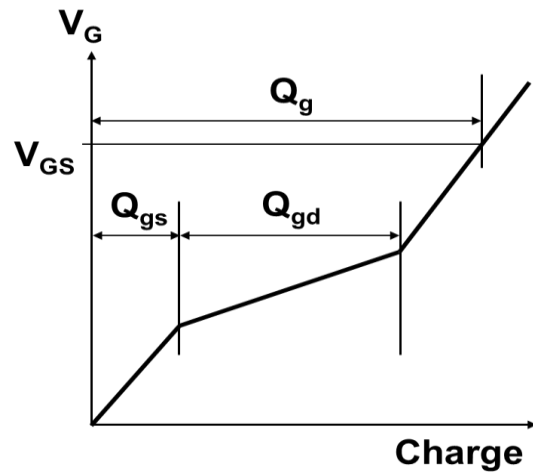


Fig.21 Dynamic Input Characteristics



\*Gate Charge Waveform



●Electrical characteristic curves

Fig.19 Typical Switching Time vs. Drain Current

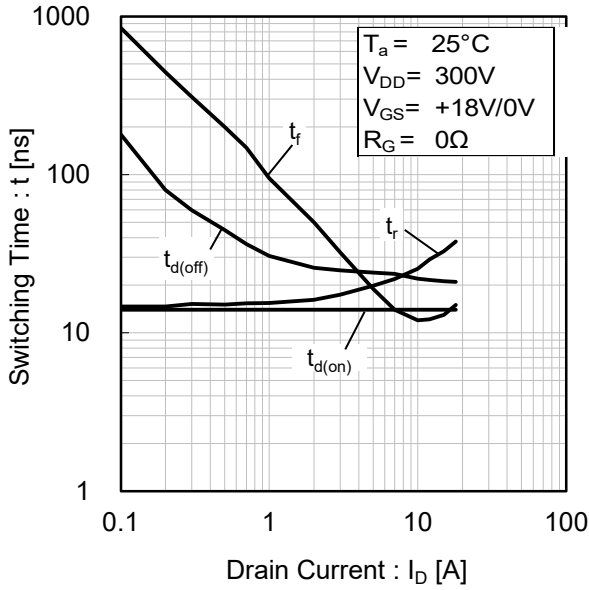


Fig.20 Typical Switching Loss vs. Drain - Source Voltage

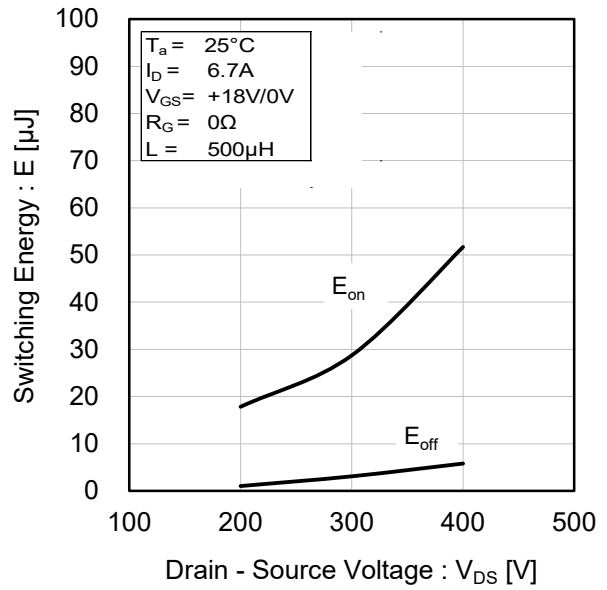


Fig.21 Typical Switching Loss vs. Drain Current

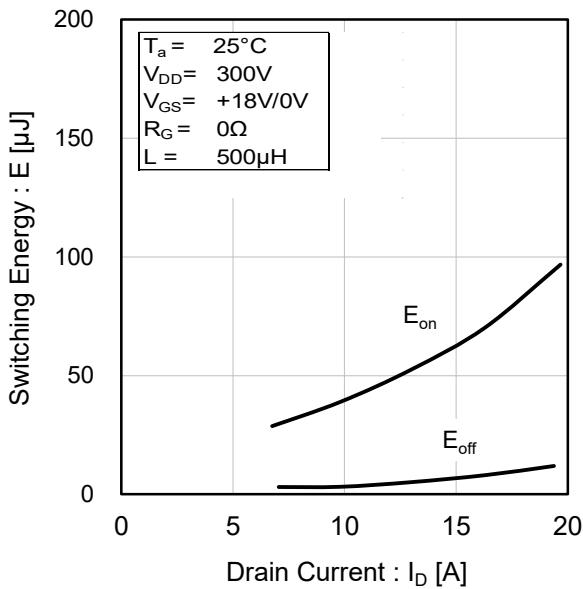
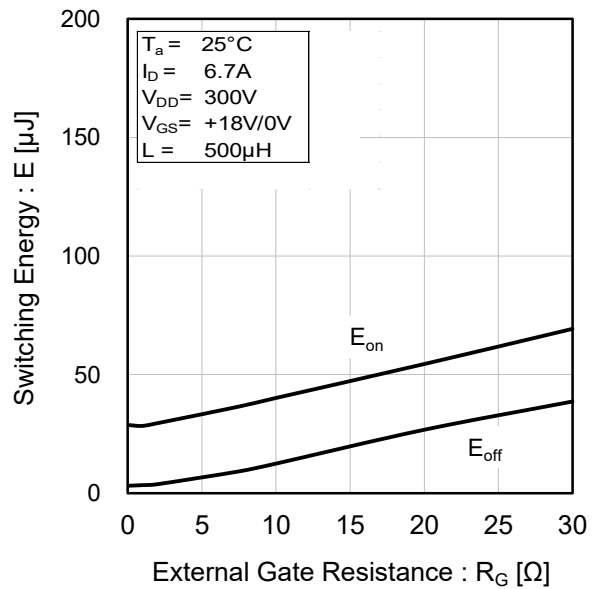


Fig.22 Typical Switching Loss vs. External Gate Resistance



● Measurement circuits and waveforms

Fig.1-1 Gate Charge and Switching Time Measurement Circuit

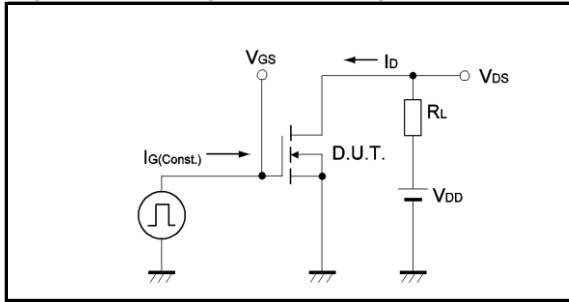


Fig.1-2 Waveforms for Switching Time

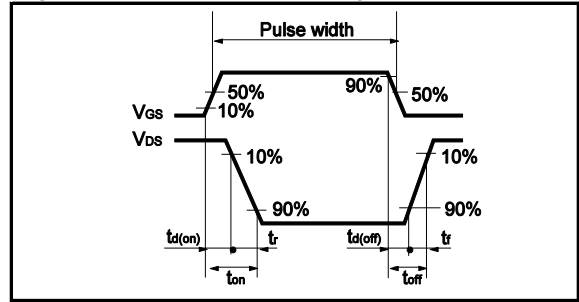


Fig.2-1 Switching Energy Measurement Circuit

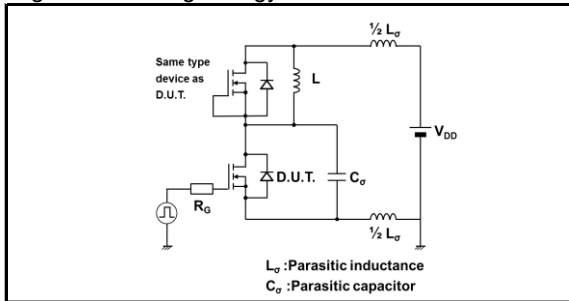


Fig.2-2 Waveforms for Switching Energy Loss

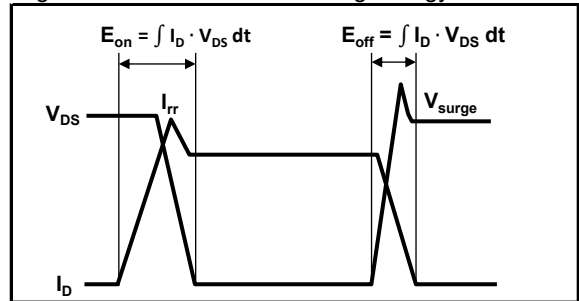


Fig.3-1 Reverse Recovery Time Measurement Circuit

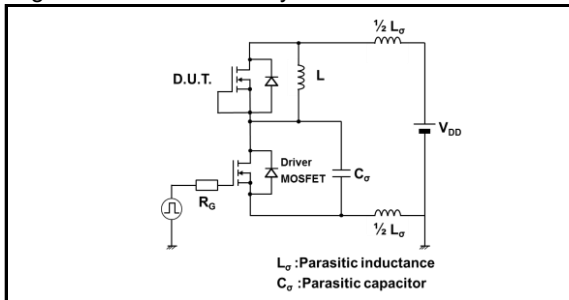
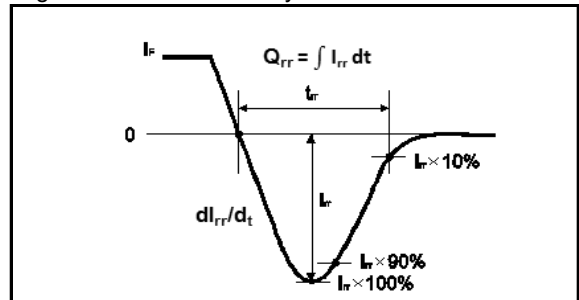


Fig.3-2 Reverse Recovery Waveform



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